# NCE2003

## N and P-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE2003 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

#### **General Features**

#### N-Channel

 $V_{DS} = 20V, I_{D} = 3A$ 

 $R_{DS(ON)}$  < 35m $\Omega$  @  $V_{GS}$ =4.5V

 $R_{DS(ON)}$  < 55m $\Omega$  @  $V_{GS}$ =2.5V

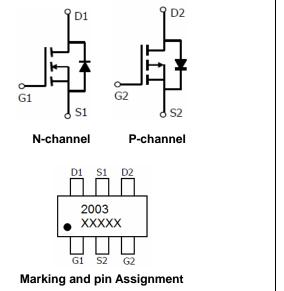
#### P-Channel

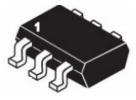
 $V_{DS} = -20V, I_{D} = -3A$ 

 $R_{DS(ON)}$  < 75m $\Omega$  @  $V_{GS}$ =-4.5V

 $R_{DS(ON)}$  < 100m $\Omega$  @  $V_{GS}$ =-2.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package





SOT-23-6L top view

## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2003	NCE2003	SOT-23-6L	Ø180mm	8mm	3000 units

Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parame	Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		V <sub>DS</sub>	20	-20	V	
Gate-Source Voltage	V <sub>GS</sub>	±12	±12			
Continuous Dunin Current	T <sub>A</sub> =25°C		3	-3	А	
Continuous Drain Current	T <sub>A</sub> =70°C	l <sub>D</sub>	2.4	-2.4		
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	13	-13	Α	
Maximum Power Dissipation T <sub>A</sub> =25℃		P <sub>D</sub>	0.8	0.8	W	
Operating Junction and Storage 1	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	-55 To 150	$^{\circ}$		

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	156	°C/W
Thermal Resistance, Junction-to-Ambient (Note2)	R <sub>0JA</sub>	P-Ch	156	°C/W



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# N-CH Electrical Characteristics (T\_A=25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	22	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	0.5	0.75	1.2	V
Drain Course On State Besistance	Б	V <sub>GS</sub> =2.5V, I <sub>D</sub> =2.8A	-	36	55	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	28	35	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}=5V,I_{D}=3A$	-	8	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>Iss</sub>	\/ 40\/\/ 0\/	-	260	-	PF
Output Capacitance	Coss	$V_{DS}$ =10V, $V_{GS}$ =0V, F=1.0MHz	-	48	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVITIZ	-	27	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	2.5	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =10V, $R_L$ =3.3 $\Omega$	-	3.2	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =4.5 $V$ , $R_{GEN}$ =6 $\Omega$	-	21	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	3	-	nS
Total Gate Charge	Qg	\/ 40\/ L 0A	-	2.9	5	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}=10V, I_{D}=3A,$	-	0.4	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =4.5V	-	0.6	-	nC
Drain-Source Diode Characteristics			•	•		
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =3 A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	3	Α

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



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# P-CH Electrical Characteristics (TA=25 ℃unless otherwise noted

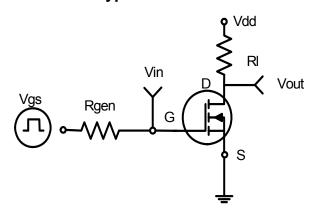
Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-20		-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V,V <sub>GS</sub> =0V	-	-	-1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=-250\mu A$	-0.4	-0.7	-1	V	
Drain-Source On-State Resistance	В	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.5 A	-	60	75	mΩ	
Diain-Source On-State Resistance		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-2A	-	81	100	mΩ	
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-2.5A	-	9.5	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V,	-	325	-	PF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V, F=1.0MHz	-	63	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	F = 1.000112	-	37	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>		-	11	-	nS	
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-10V, $R_L$ =5 $\Omega$	-	5.5	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-4.5V, $R_{GEN}$ =3 $\Omega$	-	22	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS	
Total Gate Charge	$Q_g$	\/ - 10\/   - 24	-	3.2	-	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =-10V, $I_{D}$ =-2A, $V_{GS}$ =-4.5V	-	0.6	-	nC	
Gate-Drain Charge	$Q_{gd}$	VGS4.5V	-	0.9	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-3A	-	-	-1.2	V	
Diode Forward Current (Note 2)	Is		-	-	-3	Α	

### Notes:

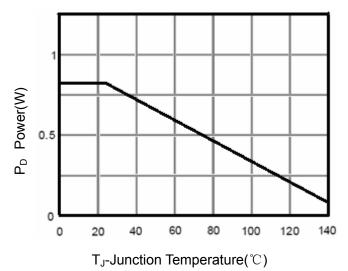
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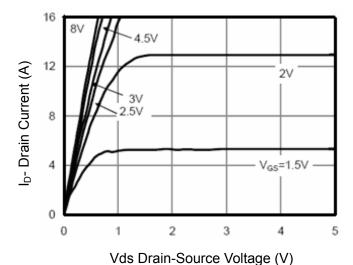
## N- Channel Typical Electrical and Thermal Characteristics (Curves)



**Figure 1:Switching Test Circuit** 



**Figure 3 Power Dissipation** 



**Figure 5 Output Characteristics** 

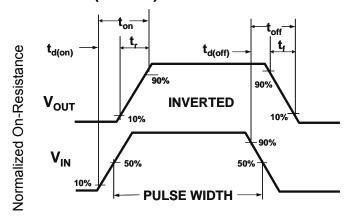
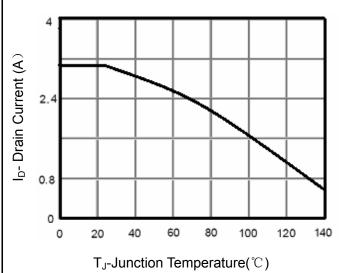
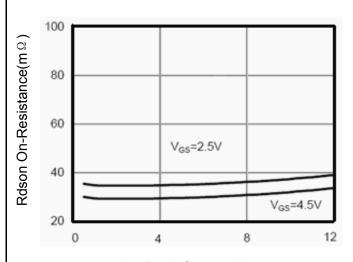


Figure 2:Switching Waveforms

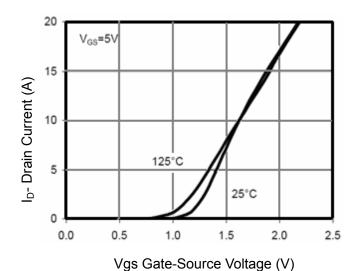


**Figure 4 Drain Current** 

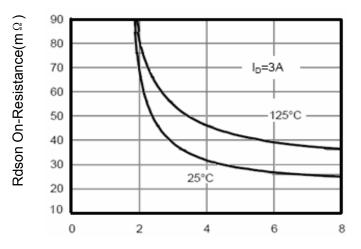


I<sub>D</sub>- Drain Current (A) Figure 6 Drain-Source On-Resistance





**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

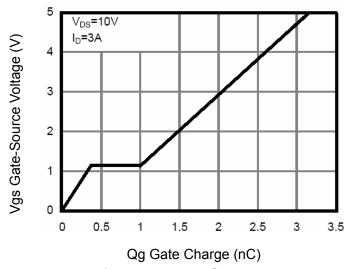
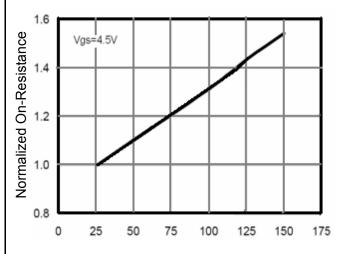
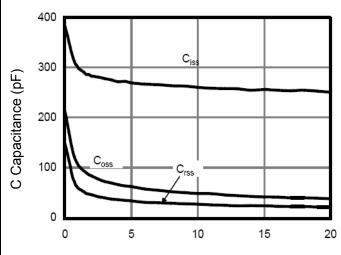


Figure 11 Gate Charge



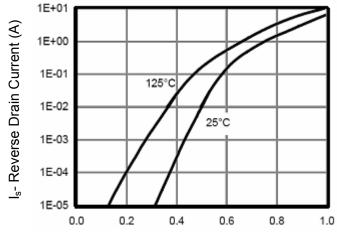
 $T_J$ -Junction Temperature( $^{\circ}$ C)





Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

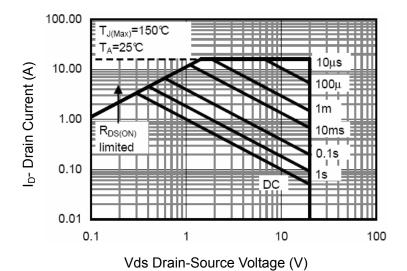


Vsd Source-Drain Voltage (V)

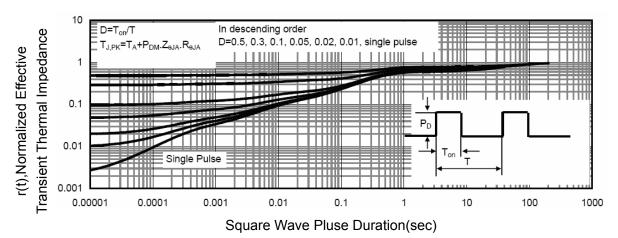
Figure 12 Source- Drain Diode Forward

**Pb Free Product** 





**Figure 13 Safe Operation Area** 

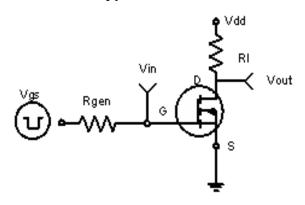


**Figure 14 Normalized Maximum Transient Thermal Impedance** 

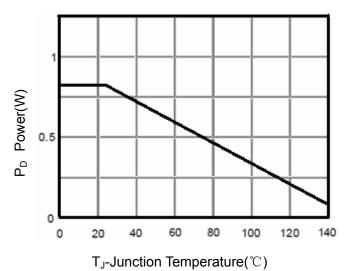
**Pb Free Product** 



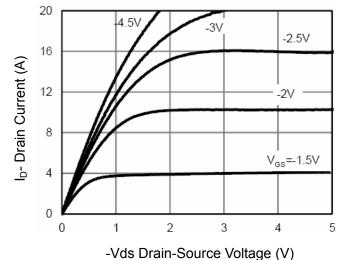
# P- Channel Typical Electrical and Thermal Characteristics (Curves)



**Figure 1:Switching Test Circuit** 



**Figure 3 Power Dissipation** 



**Figure 5 Output Characteristics** 

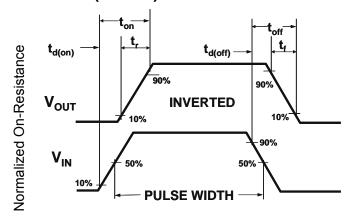
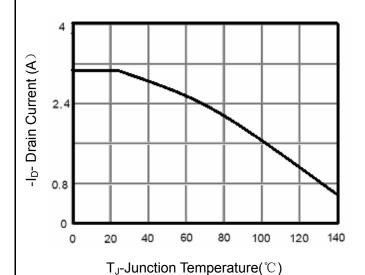


Figure 2:Switching Waveforms



**Figure 4 Drain Current** 

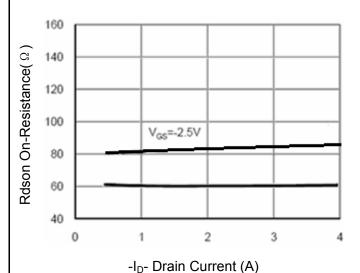
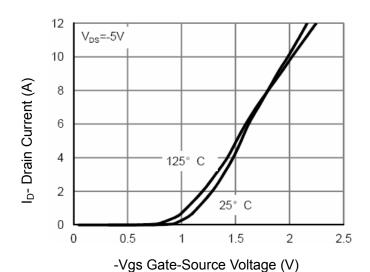


Figure 6 Drain-Source On-Resistance





**Figure 7 Transfer Characteristics** 

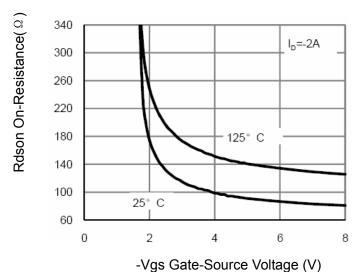


Figure 9 Rdson vs Vgs

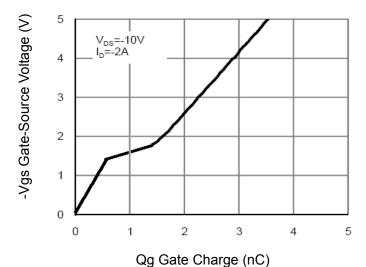
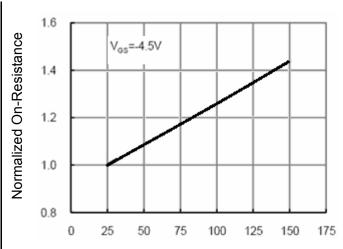


Figure 11 Gate Charge



 $T_J$ -Junction Temperature( ${}^{\circ}$ C) Figure 8 Drain-Source On-Resistance

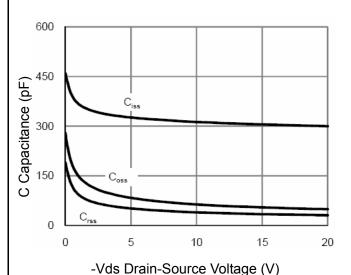


Figure 10 Capacitance vs Vds

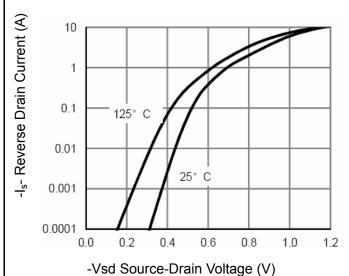
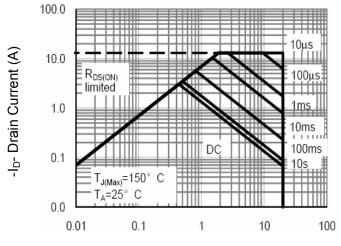


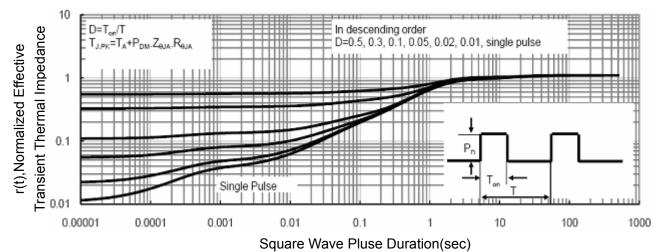
Figure 12 Source- Drain Diode Forward





-Vds Drain-Source Voltage (V)

**Figure 13 Safe Operation Area** 

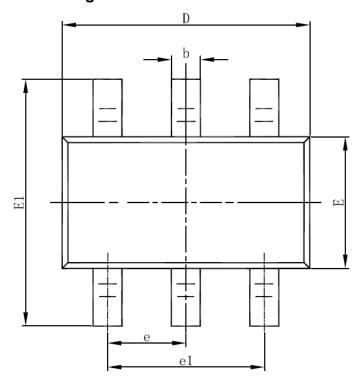


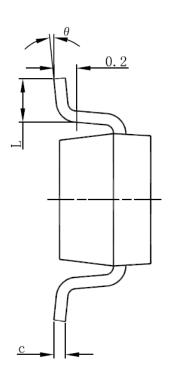
**Figure 14 Normalized Maximum Transient Thermal Impedance** 

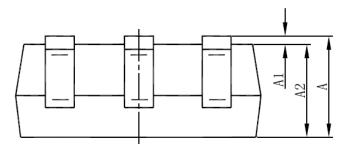


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# **SOT23-6L Package Information**







Symbol	Dimensions Ir	n Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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